

Insulated Gate Bipolar Transistor (Trench IGBT), 650 V, 120 A


SOT-227

PRIMARY CHARACTERISTICS	
V_{CES}	650 V
I_C DC	120 A at 90 °C
$V_{CE(on)}$ typical at 100 A, 25 °C	1.71 V
I_F DC	76 A at 90 °C
Speed	8 kHz to 30 kHz
Package	SOT-227
Circuit configuration	Single switch with AP diode

FEATURES

- Trench IGBT technology with positive temperature coefficient
- Square RBSOA
- FRED Pt® antiparallel diodes with ultrasoft reverse recovery
- Fully isolated package
- Very low internal inductance (≤ 5 nH typical)
- Industry standard outline
- UL pending
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


**RoHS
COMPLIANT**
BENEFITS

- Designed for increased operating efficiency in power conversion: UPS, SMPS, welding, induction heating
- Easy to assemble and parallel
- Direct mounting to heatsink
- Plug-in compatible with other SOT-227 packages
- Lower conduction losses and switching losses
- Low EMI, requires less snubbing

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	V_{CES}		650	V
Continuous collector current	I_C	$T_C = 25\text{ °C}$	167	A
		$T_C = 90\text{ °C}$	120	
Pulsed collector current	I_{CM}		220	
Clamped inductive load current	I_{LM}		220	
Diode continuous forward current	I_F	$T_C = 25\text{ °C}$	110	
		$T_C = 90\text{ °C}$	76	
Single pulse forward current	I_{FSM}	10 ms sine or 6 ms rectangular pulse, $T_J = 25\text{ °C}$	550	A
Gate-to-emitter voltage	V_{GE}		± 20	V
Power dissipation, IGBT	P_D	$T_C = 25\text{ °C}$	577	W
		$T_C = 90\text{ °C}$	327	
Power dissipation, diode	P_D	$T_C = 25\text{ °C}$	238	
		$T_C = 90\text{ °C}$	135	
Isolation voltage	V_{ISOL}	Any terminal to case, $t = 1$ min	2500	V



ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	V _{BR(CES)}	V _{GE} = 0 V, I _C = 100 μA	650	-	-	V
Collector to emitter voltage	V _{CE(on)}	V _{GE} = 15 V, I _C = 100 A	-	1.71	2.00	
		V _{GE} = 15 V, I _C = 100 A, T _J = 125 °C	-	2.00	-	
		V _{GE} = 15 V, I _C = 100 A, T _J = 175 °C	-	2.17	-	
Gate threshold voltage	V _{GE(th)}	V _{CE} = V _{GE} , I _C = 3.3 mA	5.1	6.1	8.3	
Temperature coefficient of threshold voltage	ΔV _{GE(th)} /ΔT _J	V _{CE} = V _{GE} , I _C = 1 mA (25 °C to 125 °C)	-	-20	-	mV/°C
Collector to emitter leakage current	I _{CES}	V _{GE} = 0 V, V _{CE} = 650 V	-	1.2	50	μA
		V _{GE} = 0 V, V _{CE} = 650 V, T _J = 125 °C	-	80	-	
		V _{GE} = 0 V, V _{CE} = 650 V, T _J = 175 °C	-	2.0	-	mA
Forward voltage drop, diode	V _{FM}	I _C = 100 A, V _{GE} = 0 V	-	2.00	2.53	V
		I _C = 100 A, V _{GE} = 0 V, T _J = 125 °C	-	1.69	-	
		I _C = 100 A, V _{GE} = 0 V, T _J = 175 °C	-	1.55	-	
Gate to emitter leakage current	I _{GES}	V _{GE} = ± 20 V	-	-	± 660	nA

SWITCHING CHARACTERISTICS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Input capacitance	C _{iss}	V _{GE} = 0 V, V _{CE} = 30 V, f = 1.0 MHz	-	6600	-	pF			
Output capacitance	C _{oss}		-	340	-				
Reverse transfer capacitance	C _{rss}		-	180	-				
Total gate charge (turn-on)	Q _g	I _C = 100 A, V _{CC} = 400 V, V _{GE} = 15 V	-	190	-	nC			
Gate to emitter charge (turn-on)	Q _{ge}		-	65	-				
Gate to collector charge (turn-on)	Q _{gc}		-	80	-				
Turn-on switching loss	E _{on}	I _C = 100 A, V _{CC} = 325 V, V _{GE} = 15 V, R _g = 4.7 Ω, L = 500 μH	-	0.32	-	mJ			
Turn-off switching loss	E _{off}		-	1.5	-				
Total switching loss	E _{tot}		-	1.82	-				
Turn-on delay time	t _{d(on)}		Energy losses include tail and diode recovery.	-	114	-	ns		
Rise time	t _r			-	73	-			
Turn-off delay time	t _{d(off)}			-	107	-			
Fall time	t _f			-	68	-			
Turn-on switching loss	E _{on}			I _C = 100 A, V _{CC} = 325 V, V _{GE} = 15 V, R _g = 4.7 Ω, L = 500 μH, T _J = 125 °C	-	0.52		-	mJ
Turn-off switching loss	E _{off}				-	1.85		-	
Total switching loss	E _{tot}				-	2.37		-	
Turn-on delay time	t _{d(on)}	-	115		-				
Rise time	t _r	-	74		-				
Turn-off delay time	t _{d(off)}	-	114	-	ns				
Fall time	t _f	-	89	-					
Reverse bias safe operating area	RBSOA	T _J = 175 °C, I _C = 220 A, R _g = 10 Ω, V _{GE} = 15 V to 0 V, V _{CC} = 325 V, V _P = 650 V, L = 500 μH	Fullsquare						
Short circuit safe operating area	SCSOA	V _{GE} = 15 V, V _{CC} = 400 V, R _g = 4.7 Ω, V _P ≤ 650 V, T _J = 150 °C	-	-	5.5	μs			
Diode reverse recovery time	t _{rr}	I _F = 50 A, dI _F /dt = 200 A/μs, V _R = 200 V	-	72	-	ns			
Diode peak reverse current	I _{rr}		-	5.3	-	A			
Diode recovery charge	Q _{rr}		-	192	-	nC			
Diode reverse recovery time	t _{rr}	I _F = 50 A, dI _F /dt = 200 A/μs, V _R = 200 V, T _J = 125 °C	-	149	-	ns			
Diode peak reverse current	I _{rr}		-	13	-	A			
Diode recovery charge	Q _{rr}		-	974	-	nC			



THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Junction and storage temperature range	T_J, T_{Stg}		-40	-	175	°C
Junction to case	IGBT		-	-	0.26	°C/W
	Diode		-	-	0.63	
Case to heatsink	R_{thCS}	Flat, greased surface	-	0.1	-	
Weight			-	30	-	g
Mounting torque		Torque to terminal	-	-	1.1 (9.7)	Nm (lbf.in)
		Torque to heatsink	-	-	1.8 (15.9)	Nm (lbf.in)
Case style		SOT-227				

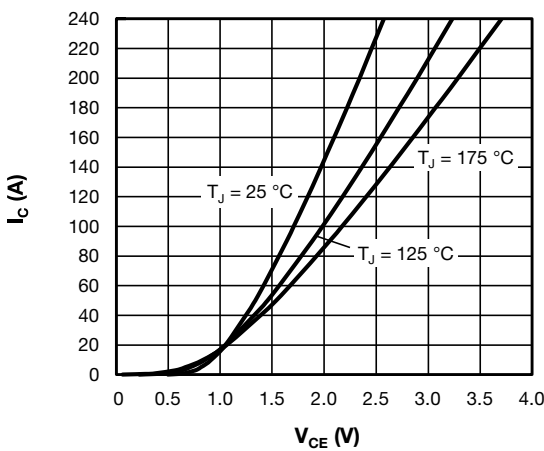


Fig. 1 - Typical IGBT Output Characteristics, $V_{GE} = 15\text{ V}$

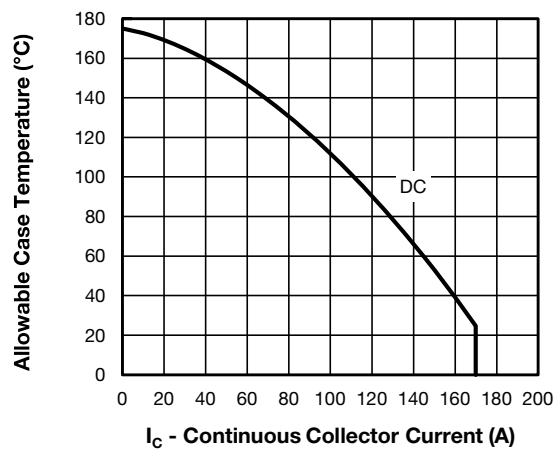


Fig. 3 - Maximum IGBT Continuous Collector Current vs. Case Temperature

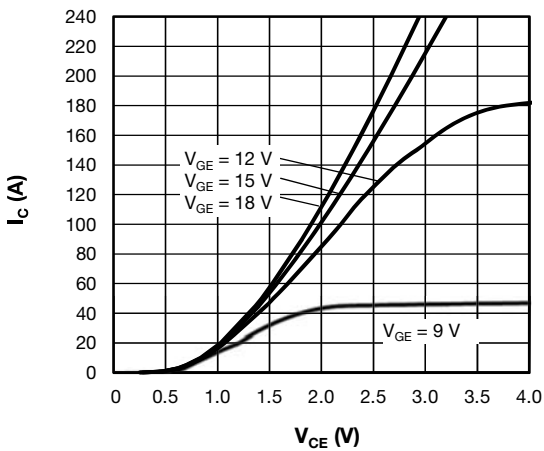


Fig. 2 - Typical IGBT Output Characteristics, $T_J = 125\text{ °C}$

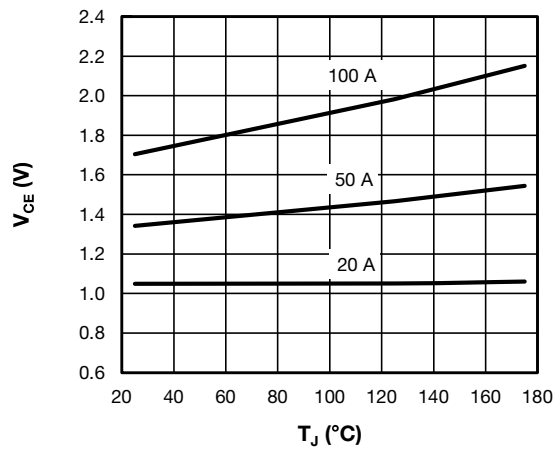


Fig. 4 - Collector to Emitter Voltage vs. Junction Temperature

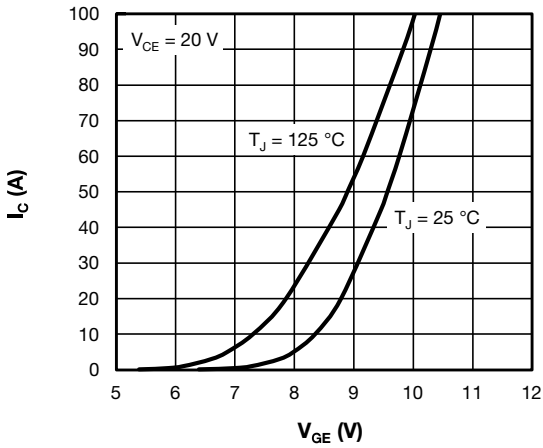


Fig. 5 - Typical IGBT Transfer Characteristics

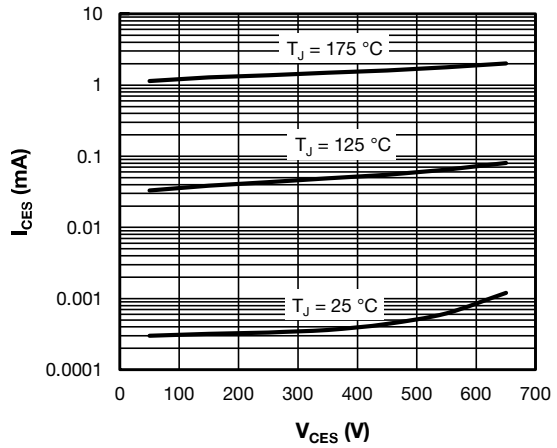


Fig. 8 - Typical IGBT Zero Gate Voltage Collector Current

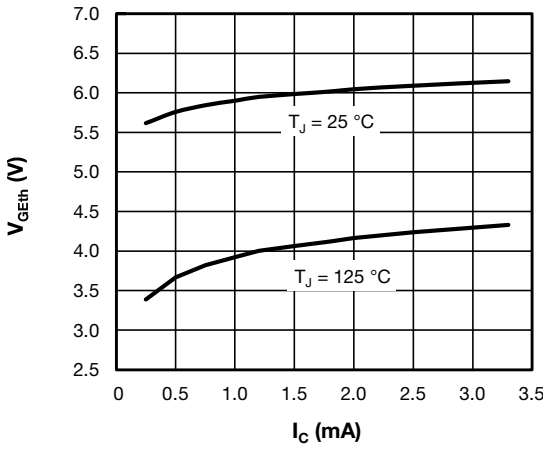


Fig. 6 - Typical IGBT Gate Threshold Voltage

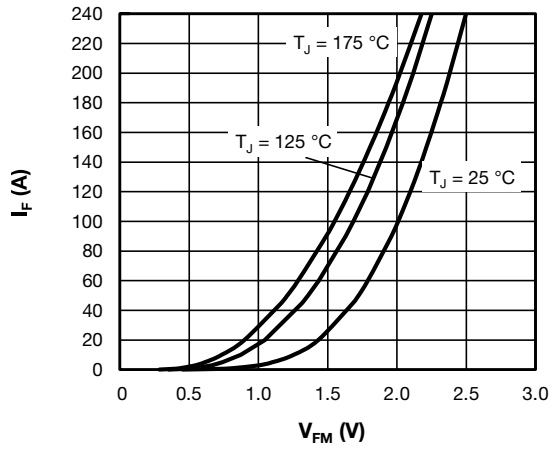


Fig. 9 - Typical Diode Forward Characteristics

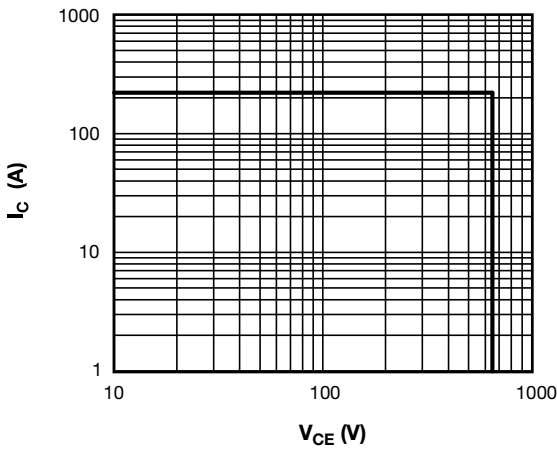


Fig. 7 - IGBT Reverse BIAS SOA $T_J = 175\text{ }^\circ\text{C}$, $V_{GE} = 15\text{ V}$

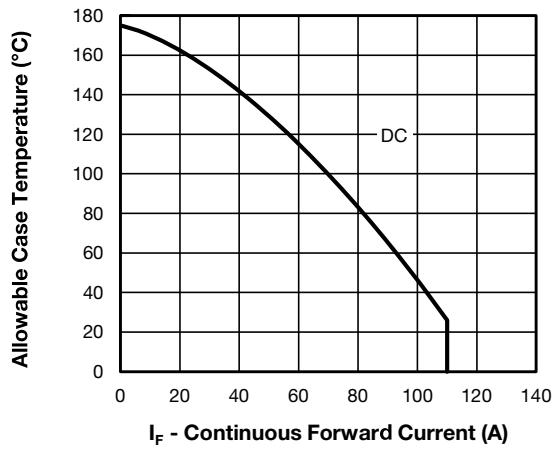


Fig. 10 - Maximum Diode Continuous Forward Current vs. Case Temperature

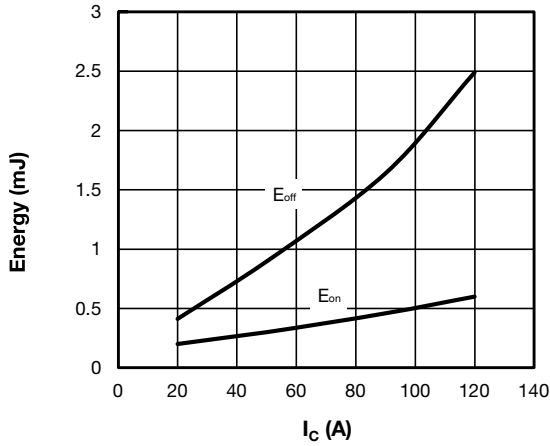


Fig. 11 - Typical IGBT Energy Loss vs. I_C
 $T_J = 125\text{ }^\circ\text{C}$, $V_{CC} = 325\text{ V}$, $R_g = 4.7\text{ }\Omega$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$

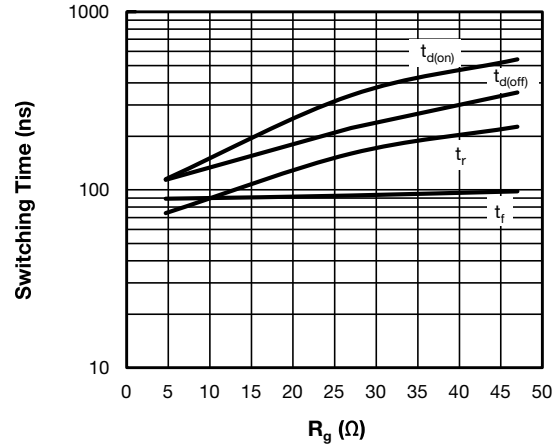


Fig. 14 - Typical IGBT Switching Time vs. R_g
 $T_J = 125\text{ }^\circ\text{C}$, $V_{CC} = 600\text{ V}$, $I_C = 100\text{ A}$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$

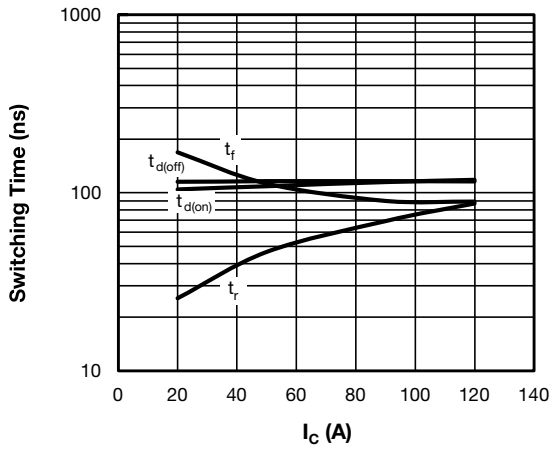


Fig. 12 - Typical IGBT Switching Time vs. I_C
 $T_J = 125\text{ }^\circ\text{C}$, $V_{CC} = 325\text{ V}$, $R_g = 4.7\text{ }\Omega$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$

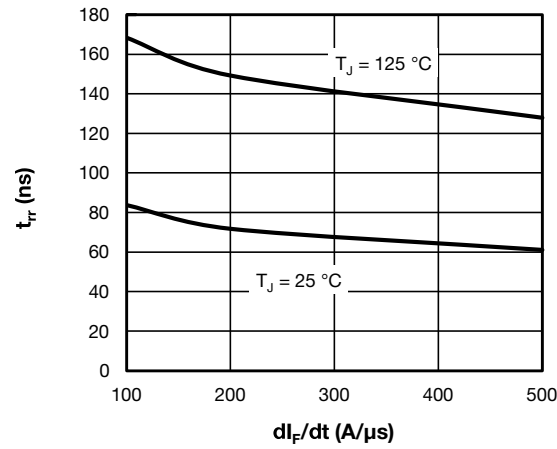


Fig. 15 - Typical t_{rr} Diode vs. dI_F/dt
 $V_{rr} = 200\text{ V}$, $I_F = 50\text{ A}$

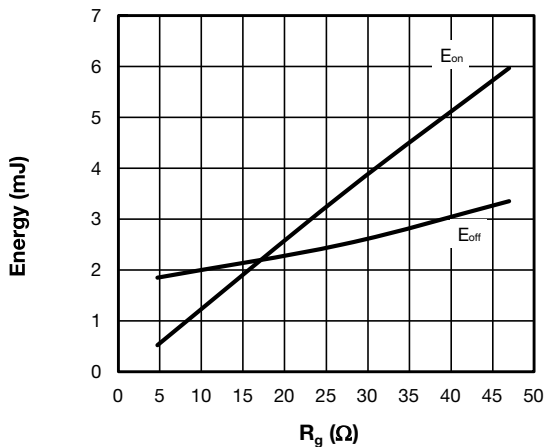


Fig. 13 - Typical IGBT Energy Loss vs. R_g
 $T_J = 125\text{ }^\circ\text{C}$, $V_{CC} = 325\text{ V}$, $I_C = 100\text{ A}$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$

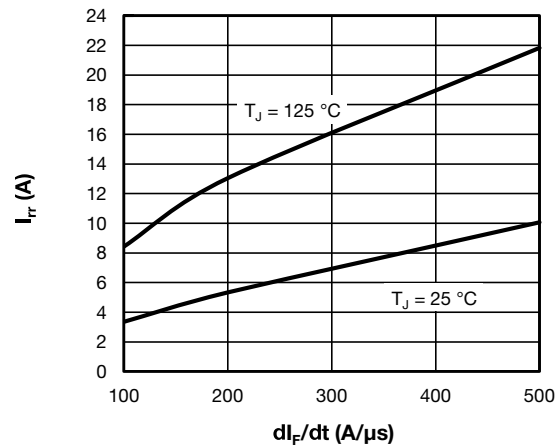


Fig. 16 - Typical I_{rr} Diode vs. dI_F/dt
 $V_{rr} = 200\text{ V}$, $I_F = 50\text{ A}$

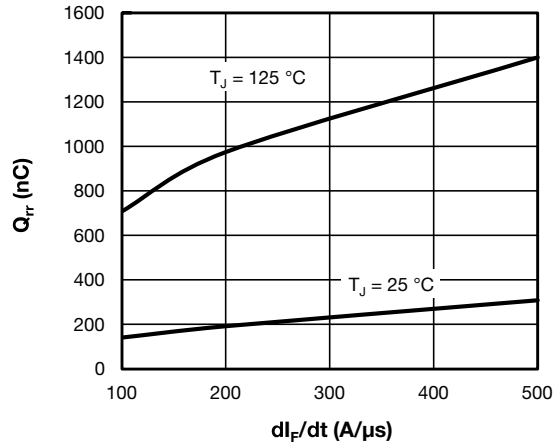


Fig. 17 - Typical Diode Reverse Recovery Charge vs. di_F/dt
 $V_{rr} = 200\text{ V}$, $I_F = 50\text{ A}$

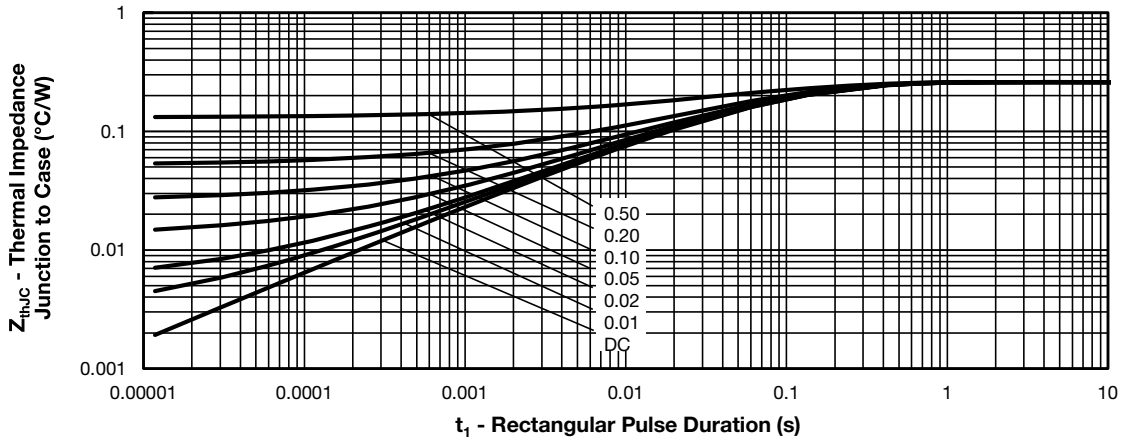


Fig. 18 - Maximum Thermal Impedance Z_{thJC} Characteristics, IGBT

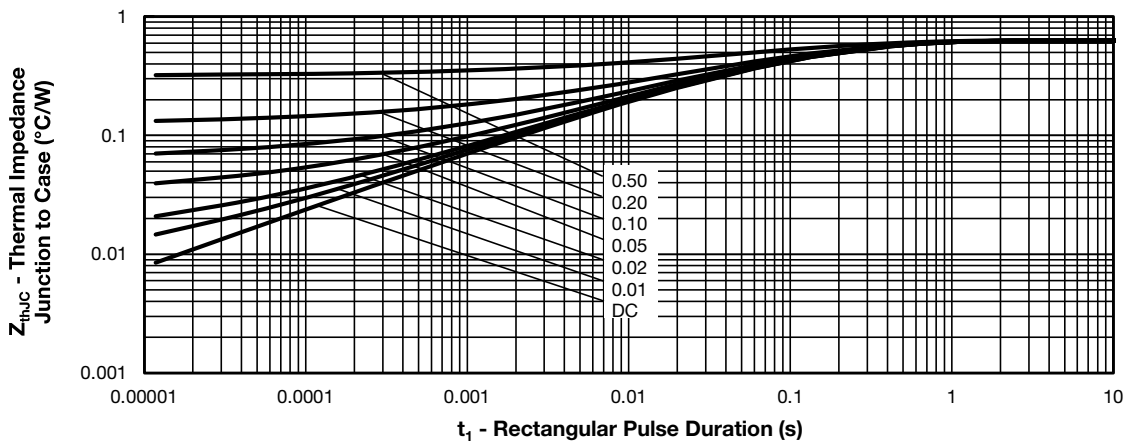


Fig. 19 - Maximum Thermal Impedance Z_{thJC} Characteristics, Diode

ORDERING INFORMATION TABLE

Device code	VS-	G	T	120	D	A	65	U
	1	2	3	4	5	6	7	8

- 1** - Vishay Semiconductors product
- 2** - Insulated gate bipolar transistor (IGBT)
- 3** - T = trench IGBT
- 4** - Current rating (120 = 120 A)
- 5** - Circuit configuration (D = single switch with antiparallel diode)
- 6** - Package indicator (A = SOT-227)
- 7** - Voltage rating (65 = 650 V)
- 8** - Speed/type (U = ultrafast IGBT)

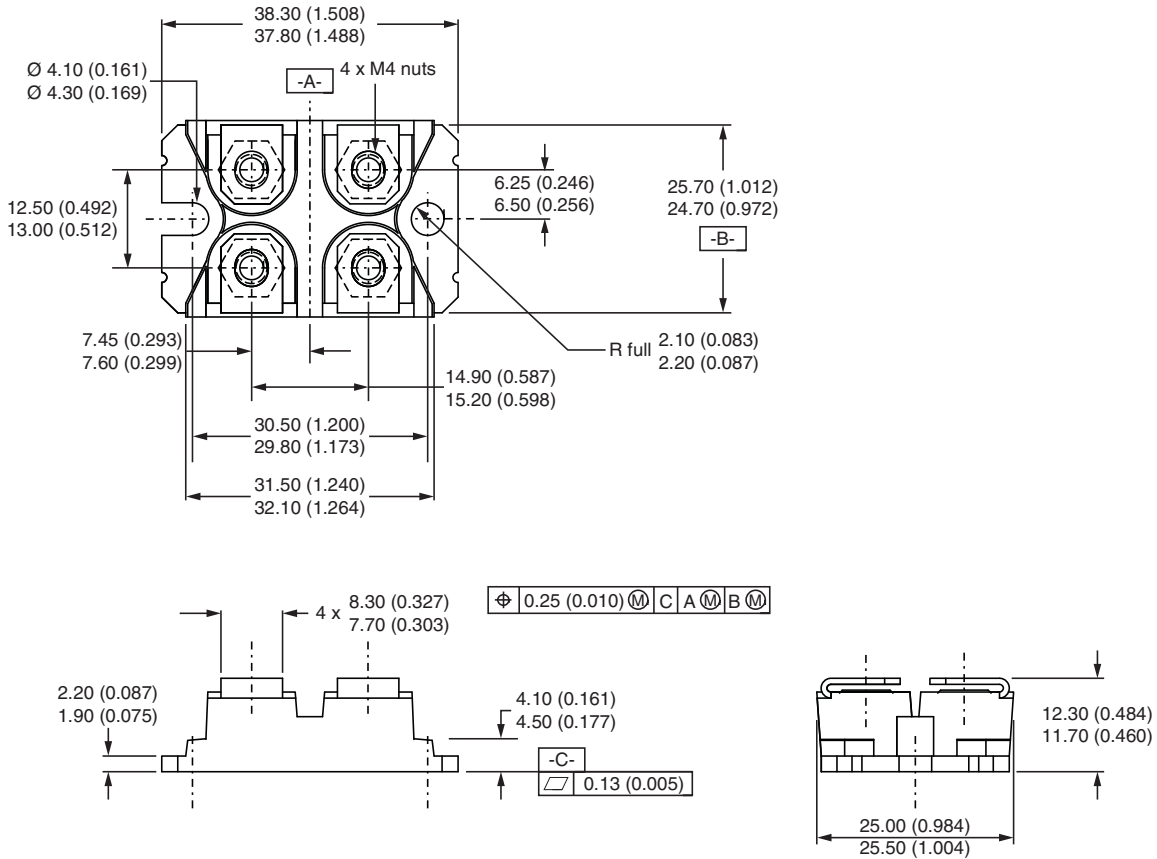
CIRCUIT CONFIGURATION		
CIRCUIT	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING
Single switch with AP diode	D	

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95423
Packaging information	www.vishay.com/doc?95425



SOT-227 Generation II

DIMENSIONS in millimeters (inches)



Note

- Controlling dimension: millimeter



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